MA3D752 (MA7D52), MA3D752A (MA7D52A)

Silicon epitaxial planar type (cathode common)

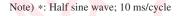
For switching mode power supply

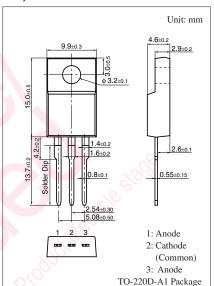
■ Features

- Low forward voltage V_F
- High dielectric breakdown voltage: > 5 kV
- Easy-to-mount, due to its V cut lead end

■ Absolute Maximum Ratings $T_a = 25^{\circ}C$

Parameter		Symbol	Rating	Unit	
Repetitive peak	MA3D752	V _{RRM}	40	V	
reverse voltage	MA3D752A		45		
Non-repetitive peak	MA3D752	V _{RSM}	40	V	
forward surge voltage					
Forward current (Average)		I _{F(AV)}	20	A	
Non-repetitive peak forward		I_{FSM}	120	A	
surge current *				,	
Junction temperature		T _j	-40 to +125	°C	
Storage temperature		T_{stg}	-40 to +125	°C	



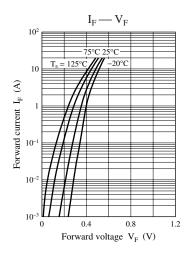


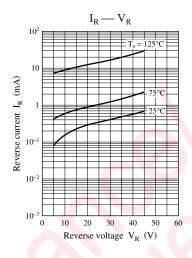
■ Electrical Characteristics $T_a = 25$ °C ± 3 °C

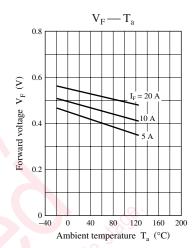
Parameter Symbo		Symbol	Conditions	Min	Тур	Max	Unit
Forward voltage		$V_{\rm F}$	$I_F = 10 \text{ A}, T_C = 25^{\circ}\text{C}$	1.90		0.55	V
Reverse current	MA3D752	I_R	$V_R = 40 \text{ V}, T_C = 25^{\circ}\text{C}$			5	mA
*	MA3D752A		$V_R = 45 \text{ V}, T_C = 25^{\circ}\text{C}$			5	
Thermal resistance (j-c)		R _{th(j-c)}	160, 175			3.0	°C/W

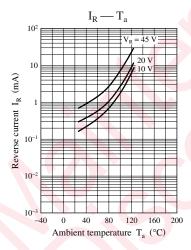
- Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 measuring methods for diodes.
 - 2. This product is sensitive to electric shock (static electricity, etc.). Due attention must be paid on the charge of a human body and the leakage of current from the operating equipment.
 - 3. Absolute frequency of input and output is 100 MHz.

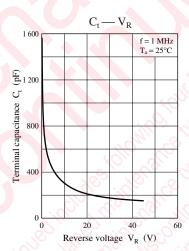
Note) The part numbers in the parenthesis show conventional part number.

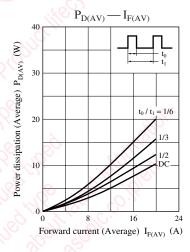


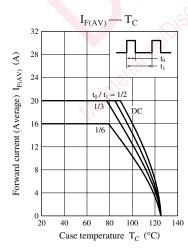












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